What is claimed is:

1. A method for securing a printed circuit board to an underlying surface comprising steps of:

applying a liquid adhesive to the underlying surface;

applying a first cure to the liquid adhesive after application of the liquid adhesive to produce a liquid adhesive that is at least partially cured;

placing the printed circuit board on the at least partially cured liquid adhesive; and

applying a second cure to the liquid adhesive to produce a printed circuit board that is secured to the underlying surface.

2. The method of claim 1, wherein the step of applying a liquid adhesive to the underlying surface comprises a step of screening the liquid adhesive onto the underlying surface.

3. The method of claim 1, wherein the step of a applying a first cure to the liquid adhesive comprises a step of exposing selected areas of the liquid adhesive to a curing element.

4. The method of claim 1, wherein the liquid adhesive is a dual-cure system adhesive.

5. The method of claim 4, wherein the liquid adhesive is a B-stage epoxy.

6. The method of claim 1, wherein the first cure of the liquid adhesive produces a tacky adhesive that spreads, at most, a negligible amount when the printed circuit board is placed on the at least partially-cured liquid adhesive.

7. The method of claim 1, wherein the printed circuit board is a flexible printed circuit board and wherein the underlying surface is a top surface of a rigidizer to which the flexible printed circuit board is secured.

8. The method of claim 7, further comprising a step of bending the printed circuit board and the rigidizer after the second cure of the liquid adhesive.

9. The method of claim 1, wherein the underlying surface is a surface of a heat sink.

10. The method of claim 1, wherein the liquid adhesive is a heat-curable liquid adhesive, wherein the first cure comprises applying a first heating stage to the liquid adhesive and wherein the second cure comprises applying a second heating stage to the liquid adhesive.

11. The method of claim 1, wherein the liquid adhesive can be cured by exposure to ultraviolet radiation.

12. The method of claim 1, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.

13. An electronic module comprising:

a rigidizer having a top surface;

a printed circuit board disposed on the top surface of the rigidizer; and

a liquid adhesive that secures the printed circuit board to the top surface of the rigidizer, wherein the liquid adhesive is cured in at least two stages, and wherein the printed circuit board is placed on the liquid adhesive after a first curing stage of the at least two curing stages and prior to a last curing stage of the at least two curing stages.

14. The electronic module of claim 13, wherein the rigidizer is a heat sink.

15. The electronic module of claim 13, wherein the printed circuit board is a flexible printed circuit board and wherein the rigidizer provides mechanical support for the flexible printed circuit board.

16. The method of claim 13, wherein the liquid adhesive is applied to the top surface of the rigidizer by a screening process.

17. The method of claim 13, wherein the first curing stage comprises exposing selected areas of the liquid adhesive to a curing element.

18. The method of claim 13, wherein the liquid adhesive is a dual-cure system adhesive.

19. The method of claim 18, wherein the liquid adhesive is a B-stage epoxy.

20. The method of claim 13, wherein the printed circuit board is a flexible printed circuit board and wherein the printed circuit board and the rigidizer are bent after the second cure of the liquid adhesive.